About the Conference : The purpose of International Conference on Emerging Trends in Technology, Science, Management and Upcoming Research in Computer Science is to bring together leading researchers, engineers and scientists in the domain of interest from India. We warmly welcome previous & prospected author to submit your new research papers to ICTSM-RCS-2023 and share the valuable experiences with the scientist and scholars. All full paper submissions will be peer reviewed and evaluated based on novelty, technical and/or research content, relevance with the theme and contributions. Selected Papers will be published in conference proceedings with ISBN number. Participant who wishes to publish their papers in Scopus Indexed Journal will be published with additional fee.

About the College: Vision: To be a world class leader in transforming lives through an innovative, rigorous and compassionate approach by imparting high quality academic excellence in technical education to uplift the living standards of the rural youth by promoting the cutting edge technologies, employability, higher education and research with socio-ethical, eco-friendly and entrepreneurial values.

Mission: To develop high quality technical personnel with a sound footing on basic engineering principles, innovative research capabilities and exemplary professional conduct to lead and to use technology for the progress of mankind, training and adepting them to changing technological environment by providing the high quality instruction, infra, faculty, effective teaching and learning methods imbibing socio-ethical, eco-friendly and entrepreneurial values as the inner strength for rural development

**Quality Policy: We, at Tirumala Engineering College, Strongly** believe that Quality is the essence of life. Hence, TEC will constantly strive to improve the quality of education and training imparted to its students by establishing state-of-theart laboratories and modernizing them continually, upgrading the knowledge and skills of its staff periodically and developing strong linkages with industry.

Mail: submit@conferenceworld.in Tirumala Engineering College Jonnalagadda, Narasaraopeta, Andhra Pradesh Call +91-7830301515, 9759005373

# Two Days

# International Conference on Electronics Circuits AND ADVANCE APPLICATIONS OF ARTIFICIAL INTELLIGENCE ICECAI-2013

ORGANIZER: TIRUMALA ENGINEERING COLLEGE JONNALAGADDA, NARASARAOPETA, ANDHRA PRADESH

Accredited by NAAC with 'A' Grade (Approved by AICTE, New Delhi)















Last date of paper submission: 12<sup>TH</sup>- 13<sup>TH</sup> Apr 2013

#### **CHIEF PATRONS**

Sri Bolla Brahma Naidu,

Chairman

Sri. R Satyanarayana,

Secretary & Correspondent

#### **PATRON**

Dr.Y.V.Narayana,

Principal, Tirmula Engineering College

#### **CONVENER**

Mr. T. Jagadeesh

**HOD Dept of ECE** 

#### **CO- CONVENERS**

Dr. R. Lalu Naik,

Professor, Dept. of CSE

Mr. K. Gopi,

Assoc. Prof, Dept. of IT

Mr. S. Anil Kumar,

Assoc. Prof, Dept. of CSE

#### **ORGANIZING COMMITTEE**

Dr. K. Sathish, Professor, Dept. of IT

Dr. A. Balaji, Professor, Dept. of CSE

Mr. Sk. Ansar, Assoc.Prof, Dept. of EEE

Mr. K. Midhun Kumar,

Assoc.Prof, Dept. of CIVIL

Mr. Ch. Rajini kumar, Assoc.Prof, Dept. of MECH

Mr. D. Pavan Kumar, Sr. Asst. Prof, Dept. of IT

Dr. S. Pavan, Assoc.Prof, Dept. of ECE

Dr. G.V.V.Nagaraju, Assoc.Prof, Dept. of EEE

#### INTERNATIONAL ADVISORY BOARD

Dr. Aviral Shrivastava, Arizona University, USA

**Dr. G. Neelaiah Babu**, Haramay University, Ethiopia

**Dr. Hamid Saremi**, Vice Chancellor, Azad University, Iran

Dr. K. N. Mathur, Utara University, Malaysia

Dr. Rakesh Mishra, Huddersfeid, U.K.

Dr. S. A. Siddiqui, Dhofar University, Oman

Dr. Sanjeev Khanna, University of Missouri, USA

Dr. YogeshKatare, Ontario, Canada

Er. Gurmeet Likhari, Texas USA

Prof. M. D. Farooq Khan, Nizwa College, Oman

Dr. Kapil Sharma, SAU, New Delhi

Dr. Saroj Kumar, SAU, New Delhi

#### MODE OF PRESENTATION:

- 1. Author can directly present paper through Google Meet.
- 2. Author(s), those fail to attend the conference can send the power point Presentation of maximum 10 slides on submit@conferenceworld.in
- 3. Author can record their Presentation and can share through Whats App.

#### FEE DETAILS

- ➤ Non- Author Participation (Only for attending the conference): 500 INR
- ➤ Presenting the paper in the conference (Max 3 Authors in a paper): 1000 INR
- ➤ Publication in conference proceeding with ISBN (Max 3 Authors in a paper): 1500 INR
- ➤ Publication in conference proceeding with ISBN and Publication in Journal: 2000 INR (Peer Reviewed),
- >8000 INR (Web of Science),12000 INR (Scopus)
- ➤ If More than three authors, each additional author will have to pay 500 INR.
- ➤ Page Limit 12, INR 100 will be Charge for each additional page.
- ➤ All papers will undergo a double blind peer review process and the criteria for acceptance will be based on quality, originality, technical content and relevance.

#### HIGHLIGHTS OF THE CONFERENCE:

- 1. All the accepted papers authors will be published in the international journals having ISSN & Impact factor.
- 2. Author will get two certificates, one for paper publication in Journal other for paper presentation in conference.
- 3. All the papers of the conference will be published in the conference proceeding with ISBN.
- 4. All the accepted will be indexed in Google scholar & IDIIF.

Note: Authors of selected articles will get an online conference link (Google Meet)

### Accordingly, Topics of interest for submission include, but are not limited to:

# Science, Engineering and Technology

Aeronautical and Aerospace Engineering

Agricultural Engineering

Applied Chemistry, Applied physics

Architecture and Construction

Artificial Intelligence

Automobile Engineering

Biotechnology

Ceramic Technology

Chemical Engineering

Civil Engineering

Communication Engineering

Computer Engineering

Computer Science and Engineering

Earth quake Engineering

Mathematics

Mechanical Engineering

Medical Laboratory Technology

Metallurgical Engineering

Mining Engineering

Nano Technology

Petroleum Engineering

Plastic Engineering and Technology

Polymer Engineering

Production and Industrial Engineering

Robotics

Rural Development and Technology

Software engineering

Structural engineering, Test and Testability

Textile Design, Engineering and Processing

Textile Technology

Electrical and Electronics Engineering

Electronics and Communication

Engineering

Embedded System

**Environmental Engineering** 

Food Engineering and Technology

Garment Technology

Highway Engineering

**Industrial Engineering** 

Information Technology

Instrumentation Engineering and Technolgy

Interior Design and Decoration

Leather Technology

lectronics Engineering

Library and Information Sciences

Marine Engineering

Material Science

## **Management and Commerce**

Accounting and Banking

Business and Marketing

Business ethics

Commerce

Database Management System

**Economics** 

**Energy Management** 

Entrepreneurship, Finance

Financial Development and management

Globalization

Human Rights

Leadership

Sport Science

Sustainable Development

Tourism

Human Resources accounting

Insurance and Risk Management

Logistics

Negotiation and counseling, operations management

Organizational behaviour

Production and operation

Quality management

Quantitative methods

Sales and distribution management

Strategy

Supply chain management

Tourism Management

Travel management

Multidisciplinary Studies

Communications and Media

Culture

Disaster Management

Gender Studies

Management

Marketing,

MIS

Conference Date:

12<sup>TH</sup>- 13<sup>TH</sup> Apr 2013

10:30 am To 05.00 pm

Notification of status of paper:

Within 03 days after

Within 03 days after receiving the Research paper

Last date of paper submission:

7<sup>TH</sup> Apr 2013

Submission of publication fee:

Within 03 working days from the date of acceptance

Mail: submit@conferenceworld.in Tirumala Engineering College

Jonnalagadda, Narasaraopeta, Andhra Pradesh Ph: 7830301515, 9759005373,8985298550